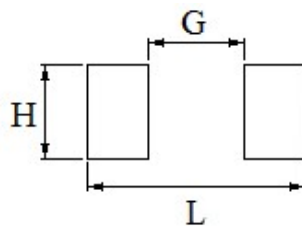


SPECIFICATION FOR APPROVAL

PAD LAYOUT: (UNIT: mm)



ITEM	L (Ref.)	G (Ref.)	H (Ref.)
SMPI02010E	2.3	0.7	2.0
SMPI02510E	2.8	1.2	2.0
SMPI02512E	2.8	1.2	2.0
SMPI03212E	3.6	1.2	2.8
SMPI03220E	3.6	1.2	2.8
SMPI04010E	4.5	1.5	4.3
SMPI04012E	4.5	1.5	4.3
SMPI04020E	4.5	1.5	4.3
SMPI04030E	4.5	1.5	4.3
SMPI04040E	4.5	1.5	4.3
SMPI05050E	5.0	2.0	4.7
SMPI06030E	5.8	2.5	5.6
SMPI06060E	5.8	2.5	5.6
SMPI07070E	6.8	2.9	6.5
SMPI10100E	9.2	3.9	9.0
SMPI15080E	15.2	6.0	15.0
SMPI15100E	15.2	6.0	15.0

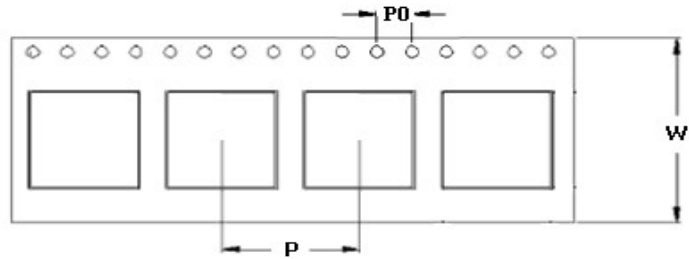


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SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	P(REF)	P0(REF)	W(REF)	BULK	PCS / REEL
SMPI02010E	4.0	4.0	8.0	v	3000
SMPI02510E	4.0	4.0	8.0	v	3000
SMPI02512E	4.0	4.0	8.0	v	3000
SMPI03212E	4.0	4.0	8.0	v	3000
SMPI03220E	4.0	4.0	8.0	v	2000
SMPI04010E	8.0	4.0	12.0	v	4000
SMPI04012E	8.0	4.0	12.0	v	4000
SMPI04020E	8.0	4.0	12.0	v	3000
SMPI04030E	8.0	4.0	12.0	v	2000
SMPI04040E	8.0	4.0	12.0	v	1500
SMPI05050E	8.0	4.0	16.0	v	1500
SMPI06030E	12.0	4.0	16.0	v	1000
SMPI06060E	12.0	4.0	16.0	v	800
SMPI07070E	12.0	4.0	16.0	v	700
SMPI10100E	16.0	4.0	24.0	v	300
SMPI15080E	24.0	4.0	32.0	v	200
SMPI15100E	24.0	4.0	32.0	v	150

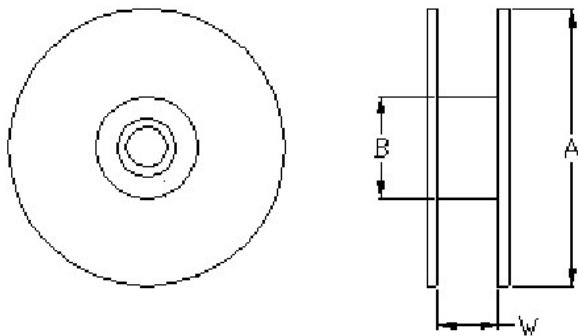


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SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	A(REF)	B(REF)	W(REF)
SMPI02010E	178	58	9.0
SMPI02510E	178	58	9.0
SMPI02512E	178	58	9.0
SMPI03212E	178	58	9.0
SMPI03220E	178	58	9.0
SMPI04010E	330	100	12.8
SMPI04012E	330	100	12.8
SMPI04020E	330	100	12.8
SMPI04030E	330	100	12.8
SMPI04040E	330	100	12.8
SMPI05050E	330	100	16.8
SMPI06030E	330	100	16.8
SMPI06060E	330	100	16.8
SMPI07070E	330	100	16.8
SMPI10100E	330	100	24.8
SMPI15080E	330	100	32.8
SMPI15100E	330	100	32.8

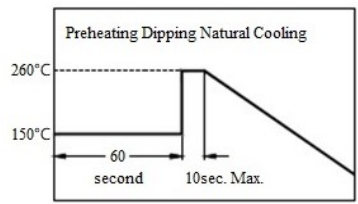
RELIABILITY AND TEST CONDITIONS:



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SPECIFICATION FOR APPROVAL

Item	Performance	Test Condition															
Operating Temperature	-40~+125°C																
Rated Current	Refer to standard electrical characteristics list.																
Temperature Rise Test	40°C max. (Δt)																
Solder heat Resistance	Appearance: No significant abnormality. Inductance change: Within $\pm 30\%$.	Preheat: 150°C, 60sec. Solder : H63A Solder temperature: 260 $\pm 0-5^\circ\text{C}$ Flux: rosin Dip time: 10sec. Max. 															
Thermal shock		Condition for 1 cycle Step1: -25 $\pm 2^\circ\text{C}$ 30 ± 3 min. Step2: Room temperature 15 min. Step3: +85 $\pm 5^\circ\text{C}$ 30 ± 3 min. Step4: Room temperature 15 min. Number of cycles: 50 <table border="1"> <thead> <tr> <th>Phase</th><th>Temperature($^\circ\text{C}$)</th><th>Time(min)</th></tr> </thead> <tbody> <tr> <td>1</td><td>-25$\pm 2^\circ\text{C}$</td><td>30± 3</td></tr> <tr> <td>2</td><td>Room Temp.</td><td>15</td></tr> <tr> <td>3</td><td>+85$\pm 2^\circ\text{C}$</td><td>30± 3</td></tr> <tr> <td>4</td><td>Room Temp.</td><td>15</td></tr> </tbody> </table>	Phase	Temperature($^\circ\text{C}$)	Time(min)	1	-25 $\pm 2^\circ\text{C}$	30 ± 3	2	Room Temp.	15	3	+85 $\pm 2^\circ\text{C}$	30 ± 3	4	Room Temp.	15
Phase	Temperature($^\circ\text{C}$)	Time(min)															
1	-25 $\pm 2^\circ\text{C}$	30 ± 3															
2	Room Temp.	15															
3	+85 $\pm 2^\circ\text{C}$	30 ± 3															
4	Room Temp.	15															
Humidity Resistance Test	Appearance: no damage Inductance: within $\pm 30\%$ of initial value.	Measured: 50 times Temperature: 40 $\pm 2^\circ\text{C}$. Applied current: rated current. Duration: 500 hrs. Humidity: 90~95%															
High Temperature Resistance Test		Temperature: 85 $\pm 2^\circ\text{C}$. Applied current: rated current. Duration: 500 hrs.															



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